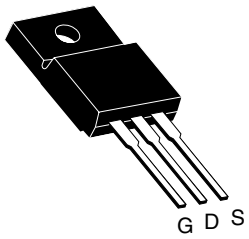
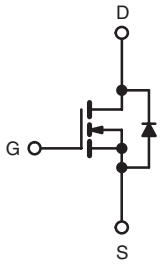
Power MOSFET

PRODUCT SUMMARY		
V_{DS} at T_J max. (V)	650	
$R_{DS(on)}$ (Ω)	V_{GS} = 10 V	0.190
Q_g (Max.) (nC)	98	
Q_{gs} (nC)	17	
Q_{gd} (nC)	25	
Configuration	Single	

TO-220 FULLPAK





N-Channel MOSFET

FEATURES

- High E_{AR} Capability
- Lower Figure-of-Merit R_{on} x Q_g
- 100 % Avalanche Tested
- High Peak Current Capability
- dV/dt Ruggedness
- Effective C_{oss} Specified
- Improved Transconductance
- Improved t_{rr}/Q_{rr}
- Improved Gate Charge
- High Power Dissipation Capability
- Compliant to RoHS Directive 2002/95/EC

Available
RoHS* COMPLIANT

ORDERING INFORMATION	
Package	TO-220 FULLPAK
Lead (Pb)-free	SiHF22N60S-E3

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	600	V
Gate-Source Voltage			V_{GS}	± 20	
Continuous Drain Current[a]	V_{GS} at 10 V	T_C = 25 °C	I_D	22	A
		T_C = 100 °C		13	
Pulsed Drain Current[b]			I_{DM}	65	
Linear Derating Factor				2	W/°C
Single Pulse Avalanche Energy[c]			E_{AS}	690	mJ
Repetitive Avalanche Energy[b]			E_{AR}	25	
Maximum Power Dissipation			P_D	250	W
Peak Diode Recovery dV/dt[d]			dV/dt	7.3	V/ns
Operating Junction and Storage Temperature Range			T_J, T_{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)[e]	for 10 s			300	

Notes

a. Limited by maximum junction temperature.
b. Repetitive rating; pulse width limited by maximum junction temperature.
c. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω, I_{AS} = 7 A.
d. I_{SD} ≤ 22 A, dI/dt ≤ 340 A/µs, V_{DD} ≤ V_{DS}, T_J ≤ 150 °C.
e. 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	**SYMBOL**	**TYP.**	**MAX.**	**UNIT**
Maximum Junction-to-Ambient	R_{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	3.4	

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 1 mA		600	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA		-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA		2.0	-	4.0	V
Gate-Source Leakage	I_{GSS}	V_{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 600 V, V_{GS} = 0 V		-	-	5	µA
		V_{DS} = 600 V, V_{GS} = 0 V, T_J = 150 °C		-	-	100	
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = 10 V	I_D = 22 A	-	0.160	0.190	Ω
Forward Transconductance[a]	g_{fs}	V_{DS} = 50 V, I_D = 13 A		-	9.4	-	S
Dynamic							
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1.0 MHz		-	2810	-	pF
Output Capacitance	C_{oss}			-	1480	-	
Reverse Transfer Capacitance	C_{rss}			-	33	-	
Effective Output Capacitance (Time Related)	$C_{oss\ eff.}$ (TR)[a]	V_{GS} = 0 V	V_{DS} = 0 V to 480 V	-	155	-	
Total Gate Charge	Q_g	V_{GS} = 10 V	I_D = 22 A, V_{DS} = 480 V	-	75	-	nC
Gate-Source Charge	Q_{gs}			-	17	-	
Gate-Drain Charge	Q_{gd}			-	25	-	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 380 V, I_D = 22 A, R_g = 9.1 Ω, V_{GS} = 10 V		-	24	-	ns
Rise Time	t_r			-	68	-	
Turn-Off Delay Time	$t_{d(off)}$			-	77	-	
Fall Time	t_f			-	59	-	
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	0.65	-	Ω
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	22	A
Pulsed Diode Forward Current	I_{SM}			-	-	88	
Diode Forward Voltage	V_{SD}	T_J = 25 °C, I_S = 22 A, V_{GS} = 0 V		-	-	1.2	V
Reverse Recovery Time	t_{rr}	T_J = 25 °C, I_F = I_S, dI/dt = 100 A/µs, V_R = 25 V		-	462	-	ns
Reverse Recovery Charge	Q_{rr}			-	8.3	-	µC
Reverse Recovery Current	I_{RRM}			-	30	-	A

Note

a. $C_{oss\ eff.}$ (TR) is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

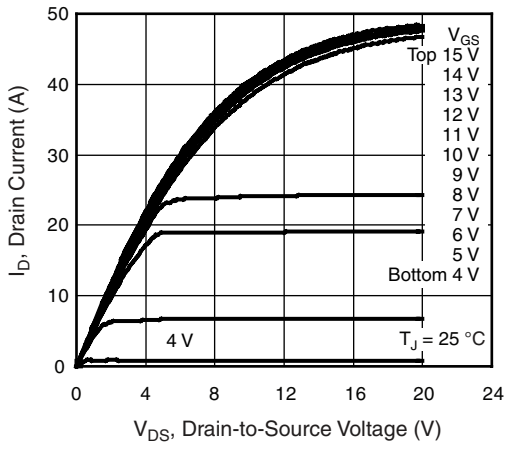


Fig. 1 - Typical Output Characteristics, T_J = 25 °C

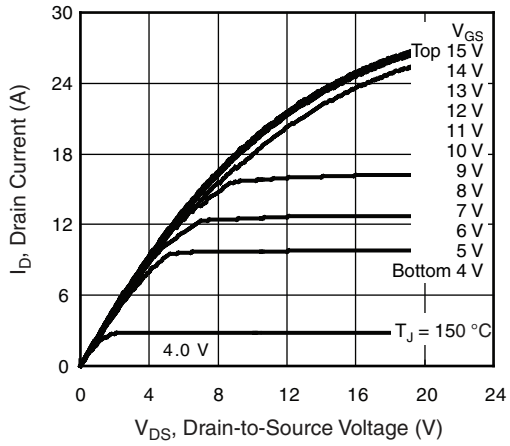


Fig. 2 - Typical Output Characteristics, T_J = 150 °C

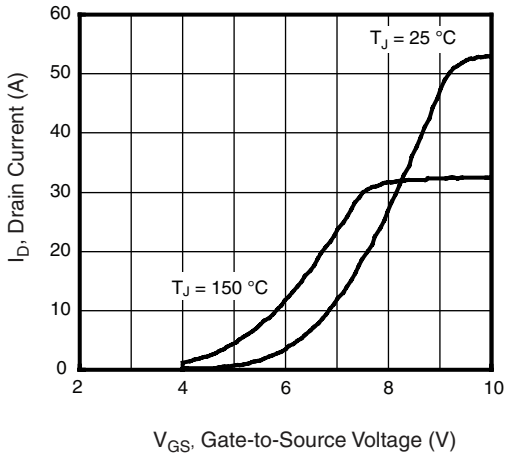


Fig. 3 - Typical Transfer Characteristics

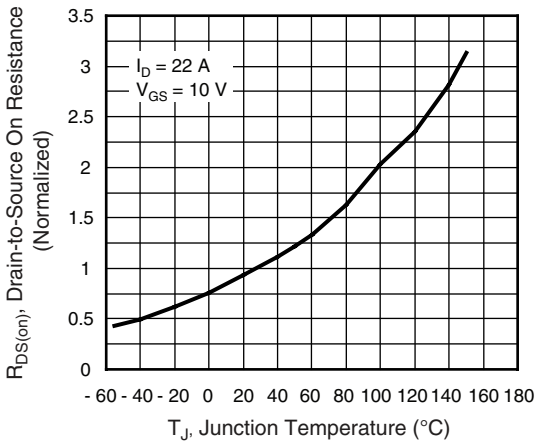


Fig. 4 - Normalized On-Resistance vs. Temperature

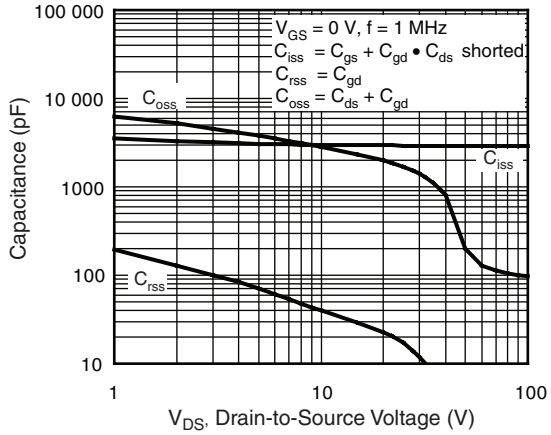


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

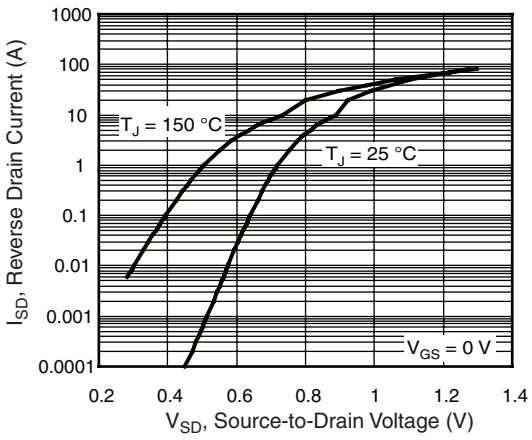


Fig. 7 - Typical Source-Drain Diode Forward Voltage

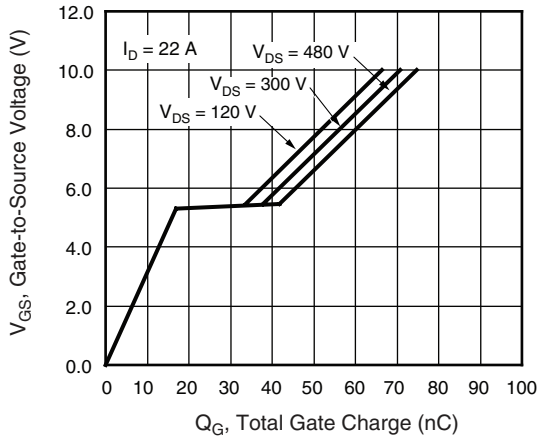


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

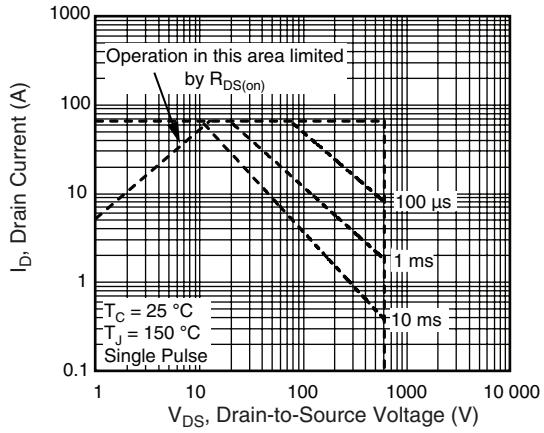


Fig. 8 - Maximum Safe Operating Area

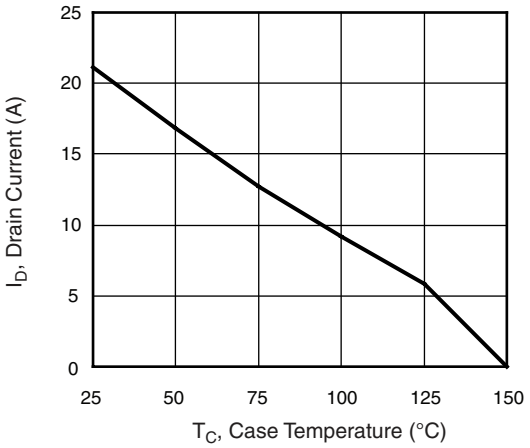


Fig. 9 - Maximum Drain Current vs. Case Temperature

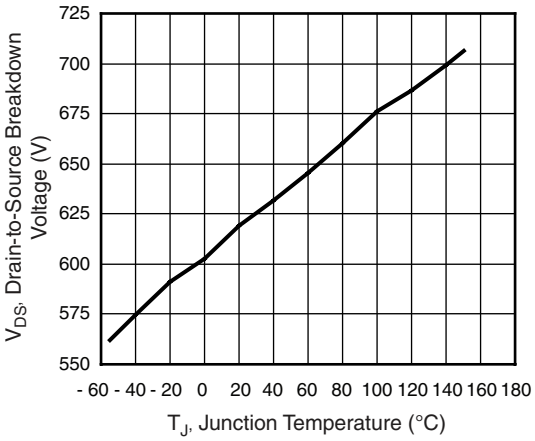


Fig. 10 - Drain-to-Source Breakdown Voltage

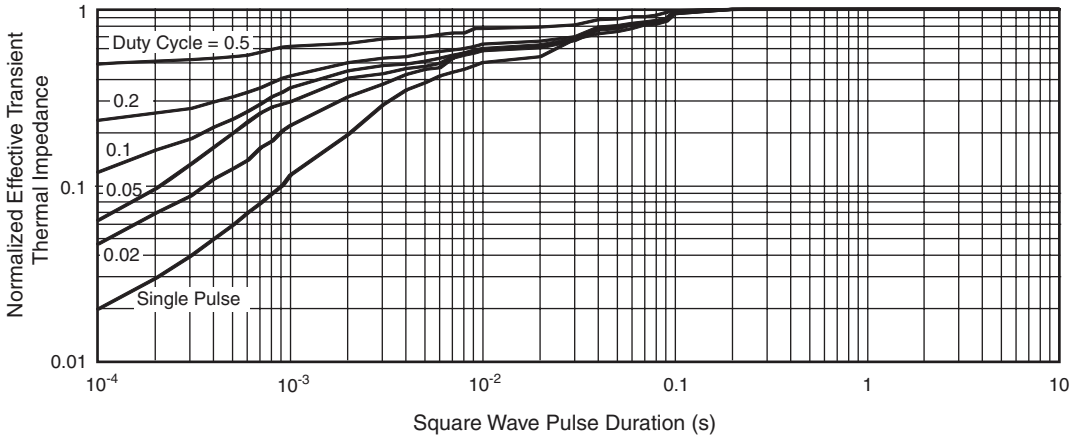


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

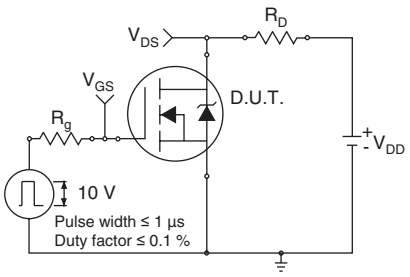


Fig. 11a - Switching Time Test Circuit

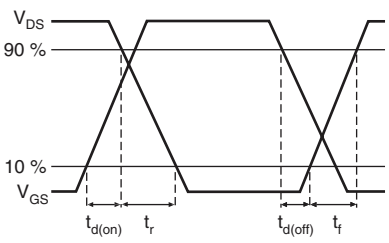


Fig. 11b - Switching Time Waveforms

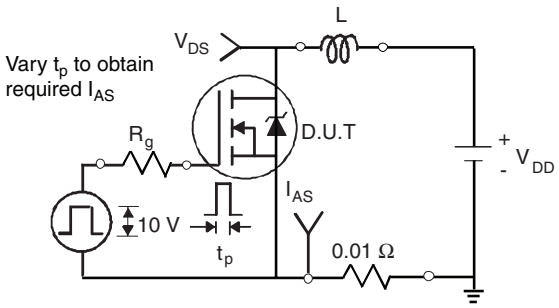


Fig. 12a - Unclamped Inductive Test Circuit

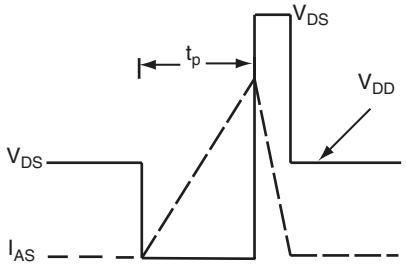


Fig. 12b - Unclamped Inductive Waveforms

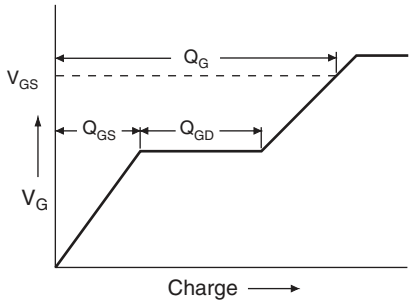


Fig. 13a - Basic Gate Charge Waveform

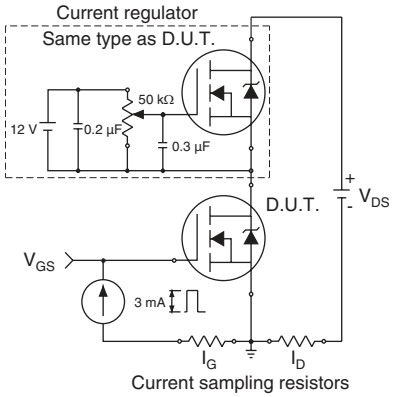
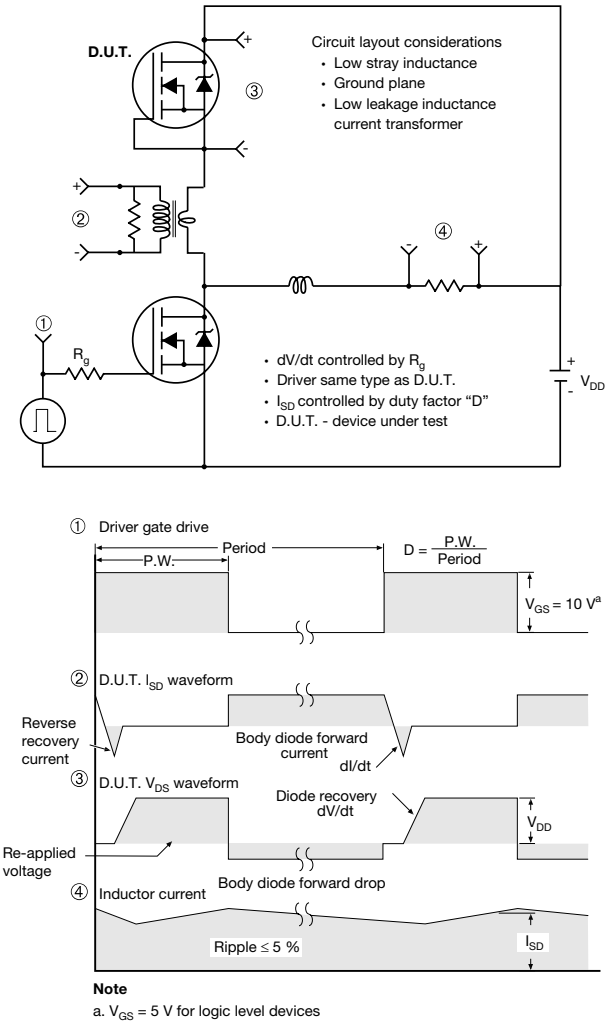


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



Note

a. V_{GS} = 5 V for logic level devices

Fig. 14 - For N-Channel

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